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**MANUFACTURE OF SEMICONDUCTOR DEVICE**

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**Abstract:**

**PURPOSE:** To reduce the irregularity in shape and size of the titled semiconductor device by a method wherein a semiconductor pellet is mounted on the printed wiring substrate on which the patterning corresponded to an element structure is provided in advance, and after the surface of the element is sealed with resin, the sealed printed wiring substrate is cut and isolated.

**CONSTITUTION:** A semiconductor pellet 3 is mounted and fixed on a printed wiring substrate 1 using solder 2, and a wiring is performed thereon using a bonding wire 4. Then, the surface of an element is sealed by resin 5, and lastly, the element is isolated by cutting and a finished article is obtained. The substrate can be isolated without damaging the coupling with the contact to be used for mounting on the back side by cutting the center part of a through hole accurately. As a result, a small-sized leadless chip carrier element of high working accuracy and excellent quality can be obtained.

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